

N-Channel 100-V (D-S) MOSFET

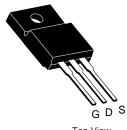
PRODUCT S	UMMARY	
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)
100	0.0085 at V _{GS} = 10 V	90
100	0.0100 at V _{GS} = 6 V	85

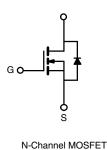
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC









ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V		
Gate-Source Voltage		V _{GS}	± 20	V		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	I _D	90			
Continuous Diain Current (1) = 150 C)	T _C = 125 °C	۵' ا	70 ^a	Α		
Pulsed Drain Current	I _{DM}	287	A			
Avalanche Current	L = 0.1 mH	I _{AS}	75			
Single Pulse Avalanche Energy ^b	L = 0.1 IIII	E _{AS}	280	mJ		
b	$T_C = 25 ^{\circ}C (TO-220F)$	P _D	56	W		
Maximum Power Dissipation ^b	T _A = 25 °C (TO-220F)	υ' υ	3.75	VV		
Operating Junction and Storage Temperatu	re Range	T_J , T_{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-220) d	- R _{thJA}	40		
Junction-to-Ambient	Free Air (TO-220)		62.5	°C/W	
Junction-to-Case		R _{thJC}	0.6		

Notes

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.0095			
	D _D	V _{GS} = 6 V, I _D = 20 A		0.0100		Ω S pF	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.0160		Ω	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.0210			
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	•			•			
Input Capacitance	C _{iss}			6550			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		665		pF	
Reverse Transfer Capacitance	C _{rss}			265			
Total Gate Charge ^c	Q_g	105			nC		
Gate-Source Charge ^c	Q _{gs}						
Gate-Drain Charge ^c	Q_{gd}	1		23			
Turn-On Delay Time ^c	t _{d(on)}			12	25		
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135	ns	
Turn-Off DelayTime ^c	t _{d(off)}	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85		
Fall Time ^c	t _f	1		130	195		
Source-Drain Diode Ratings and Char	racteristics T _C	= 25 °C ^b		•			
Continuous Current	Is			90		^	
Pulsed Current	I _{SM}			240		Α	
Forward Voltage ^a	V _{SD}	I _F = 85 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			85	140	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q _{rr}	1		0.17	0.35	μС	

Notes:

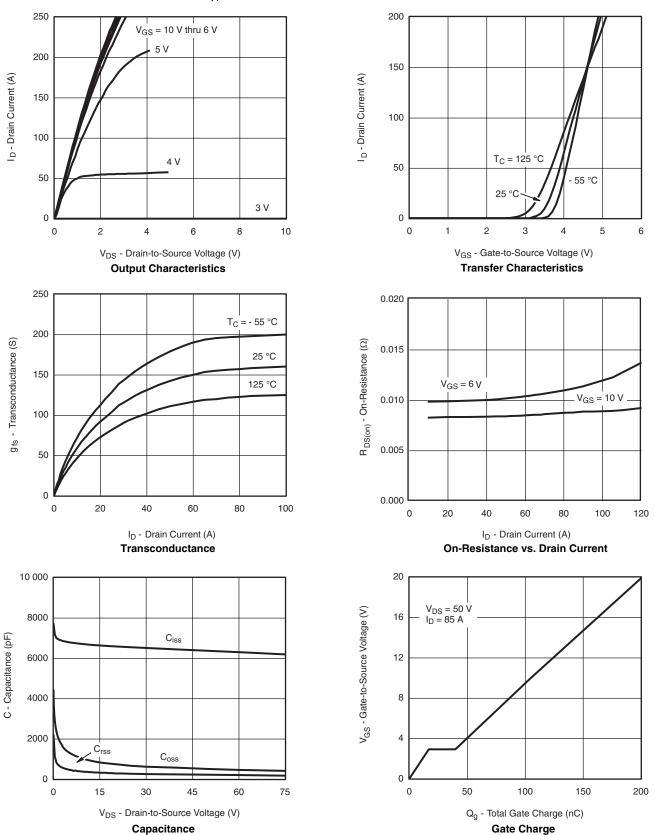
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- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



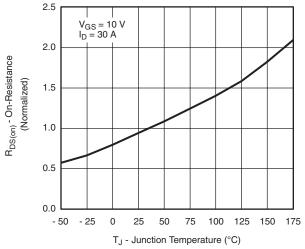
TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



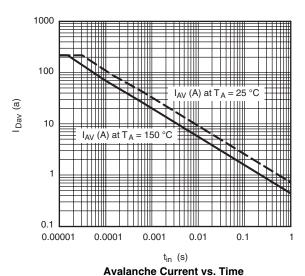
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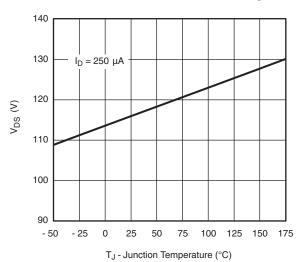
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On-Resistance vs. Junction Temperature



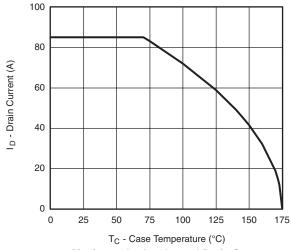
Source-Drain Diode Forward Voltage



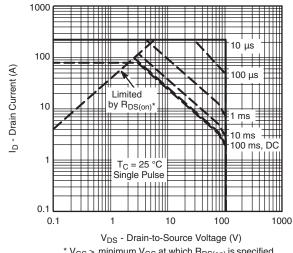
T_J - Drain-Source Breakdown vs. Junction-Temperature



THERMAL RATINGS

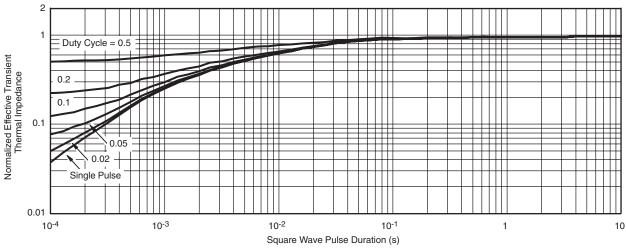


Maximum Avalanche and Drain Current vs. Case Temperature



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

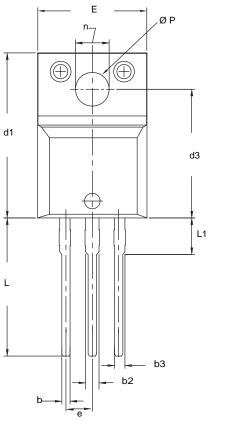
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)



D

DIM.	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100	BSC	
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
٧	0.400	0.500	0.016	0.020	

DWG: 5972

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- Notes
- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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